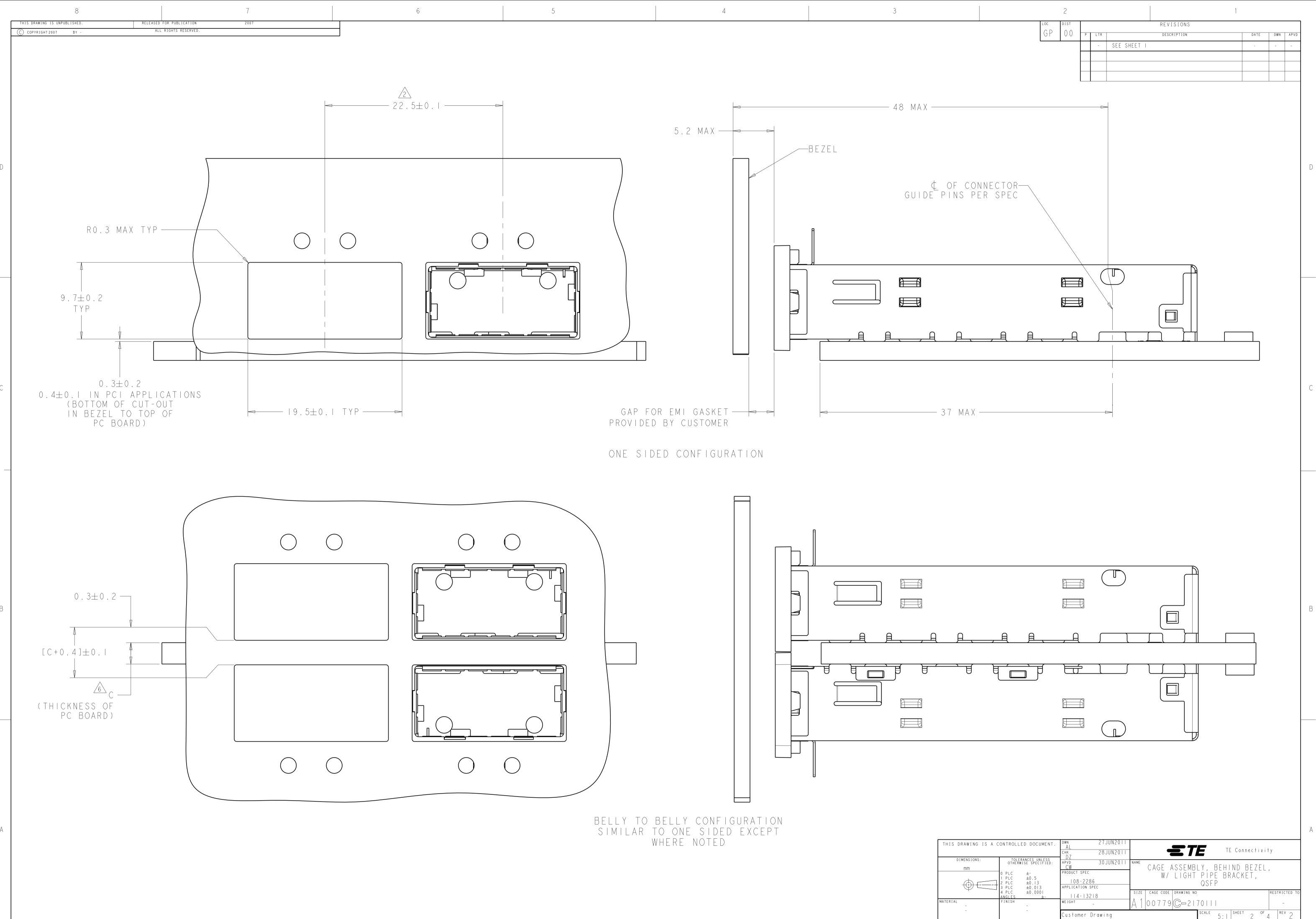


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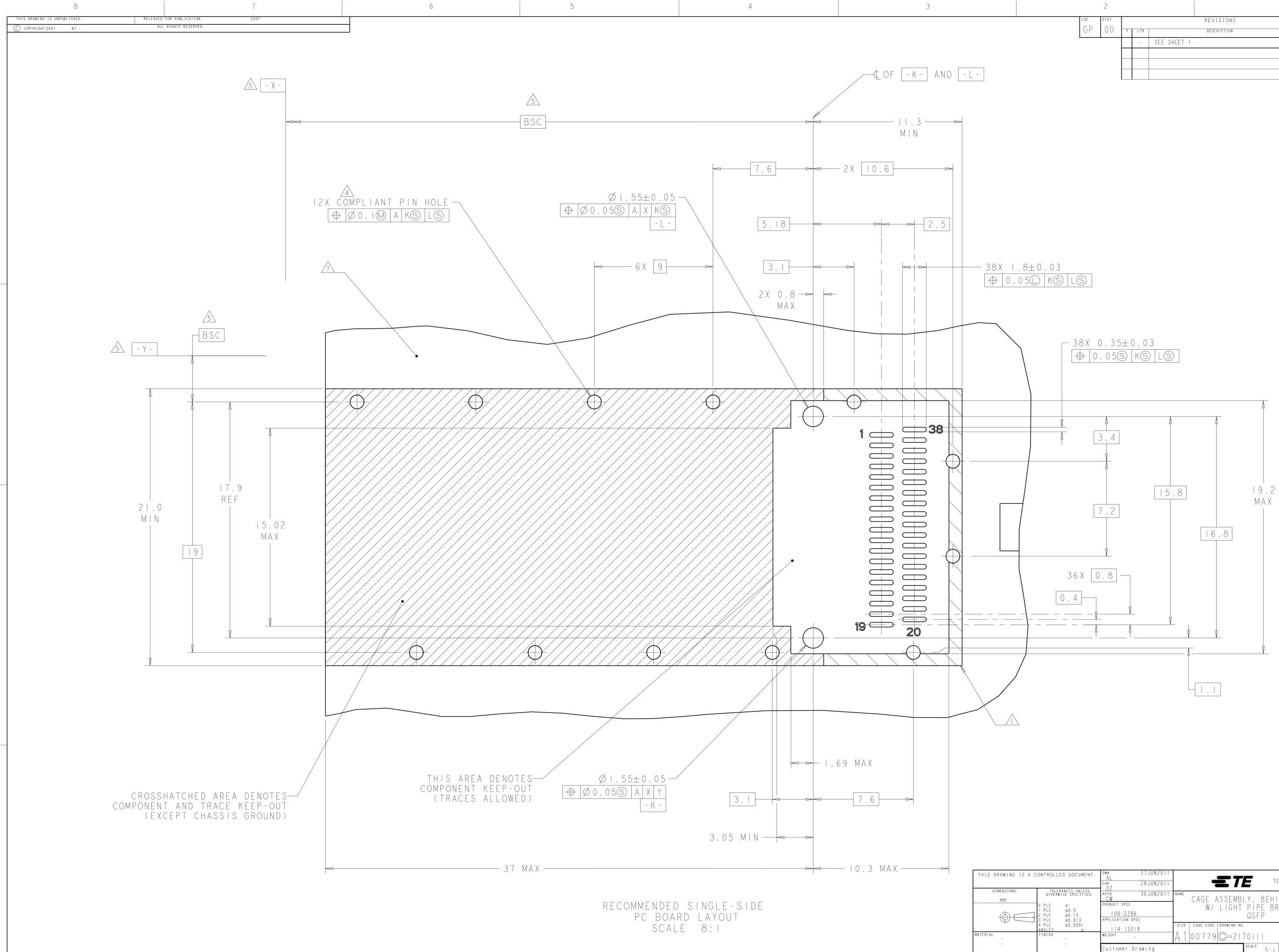
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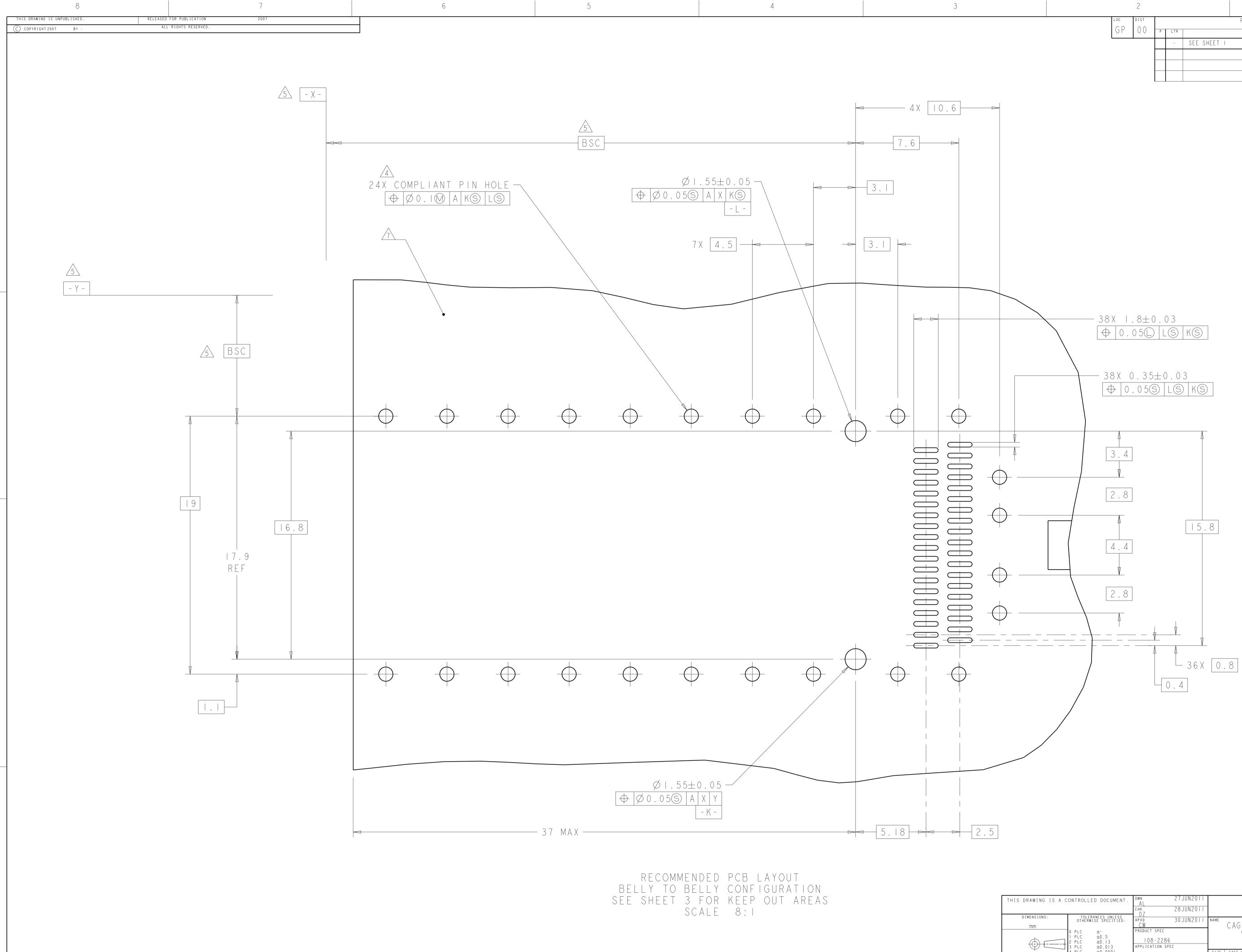


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单击下面可查看定价,库存,交付和生命周期等信息

>>TE Connectivity(泰科)